

N-Ch MOSFET

General Description

The WSD3060DN is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSD3060DN meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline

Absolute Maximum Ratings

- 100% EAS Guaranteed
- Green Device Available

Product Summery

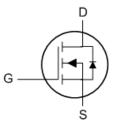
BVDSS	RDSON	ID
30V	4.7mΩ	60A

Applications

- High Frequency Point-of-Load Synchronous
 Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN3.3X3.3-8 Pin Configuration





Symbol	Parameter Rating		Units
V _{DS}	Drain-Source Voltage 30		V
V _{GS}	Gate-Source Voltage ±20		V
I₀@T₀=25℃	Continuous Drain Current, V _{GS} @ 10V ¹	60	A
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ¹	48	A
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	13	A
I _D @T _A =70℃	Continuous Drain Current, V _{GS} @ 10V ¹	10	A
I _{DM} @Тс=25℃	Pulsed Drain Current ²	140	A
EAS	Avalanche Energy ,Single Pulse (L=0.5mH) ³	100	mJ
I _{AS}	Avalanche Current ,Single pulse(L=0.5mH) ³	20	A
P _D @T _C =25℃	Total Power Dissipation ⁴	50	W
P _D @T _A =25℃	Total Power Dissipation ⁴	3.6	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹		70	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹		2.5	°C/W



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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\!{\rm C}$, $I_D\text{=}1\text{mA}$		0.028		V/℃
Б	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =40A		4.7	5.7	
R _{DS(ON)}		V _{GS} =4.5V , I _D =20A		5.8	7.6	mΩ
V _{GS(th)}	Gate Threshold Voltage	—V _{GS} =V _{DS} , I _D =250uA	1.2	1.8	2.5	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS} = V_{DS}$, $I_D = 2500A$		-6.16		mV/℃
		V _{DS} =24V , V _{GS} =0V , T _J =25°C			1	uA
I _{DSS}	Drain-Source Leakage Current	V_{DS} =24V , V_{GS} =0V , T_J =55 $^\circ \mathrm{C}$			5	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm20V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =40A		95		S
R _g	Gate Resistance	V_{DS} =0V , V_{GS} =0V , f=1MHz		2.0	2.9	Ω
Qg	Total Gate Charge (4.5V)			20	28.0	
Q _{gs}	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =40A		7.6	10.6	nC
Q _{gd}	Gate-Drain Charge			7.2	10.1	
T _{d(on)}	Turn-On Delay Time			15	28	
Tr	Rise Time	V_{DD} =15V , V_{Gen} =10V ,		13	24	20
T _{d(off)}	Turn-Off Delay Time	R _G =3.3Ω, I _D =1A, RL=10Ω.		32	57	ns
T _f	Fall Time			9	17	
C _{iss}	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		1500	1820	
C _{oss}	Output Capacitance			260	310	рF
C _{rss}	Reverse Transfer Capacitance			130	190	

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy 5	V _{DD} =25V , L=0.5mH , I _{AS} =20A	63			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}				10	А
I _{SM}	Pulsed Source Current ^{2,6}	$V_G = V_D = 0V$, Force Current			140	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25℃			1	V
t _{rr}	Reverse Recovery Time			21		nS
Qrr	Reverse Recovery Charge	l ⊧=40A , dl/dt=100A/μs , T_J=25 ℃		7		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width $\leq\,$ 300us , duty cycle $\leq\,$ 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.5mH, I_{AS} =20A

4.The power dissipation is limited by 150 $^\circ\!\!\mathbb{C}$ junction temperature

5.The Min. value is 100% EAS tested guarantee.

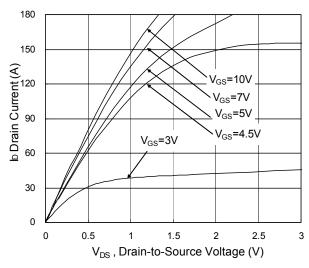
6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

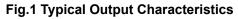


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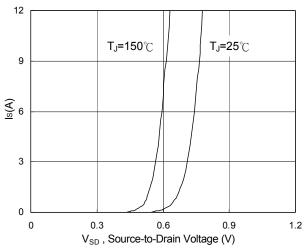


Fig.3 Forward Characteristics of Reverse

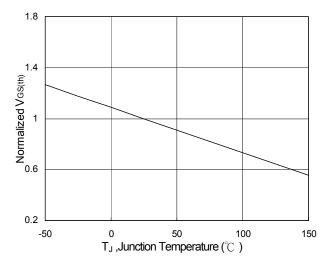


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

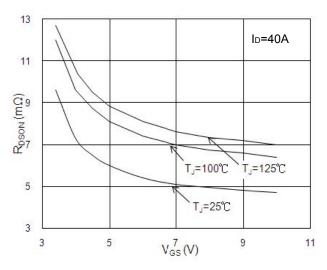


Fig.2 On-Resistance vs. G-S Voltage

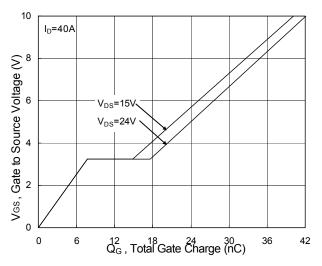
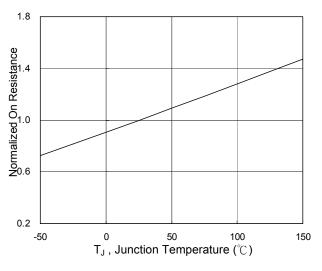
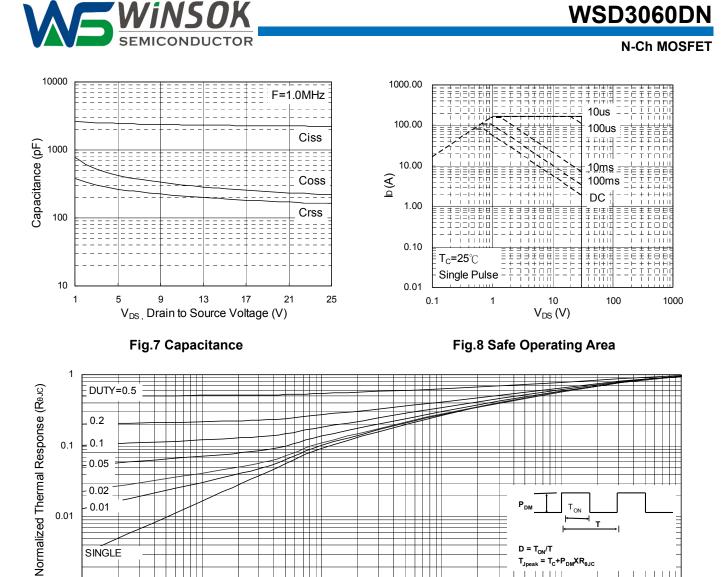


Fig.4 Gate-Charge Characteristics





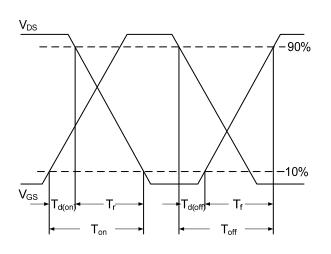




t, Pulse Width (s)

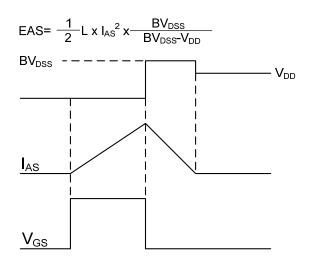
0.001

0.01



0.0001





 $D = T_{ON}/T$

T_c+P

0.1

Fig.11 Unclamped Inductive Switching Waveform

0.02 0.01

SINGLE

0.01

0.001

0.00001

1



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